

Description

The μ PD7003 is a high speed, high performance, low power, 8-bit analog-to-digital Converter designed to be easily interfaced to the 8080 and 8086, 8- and 16-bit microprocessors. Using the parallel conversion technique, the μ PD7003 features a conversion speed of 4 μ s and eliminates the need of sample and hold circuits in most applications. The μ PD7003 is also capable of running under DMA control using a DMA controller such as the μ PD8257. Available in a 24-pin ceramic/plastic DIP, the μ PD7003 is the ideal converter for high speed 8-bit designs.

Features

- ☐ High speed conversion (250 k samples/sec. max.)
 ☐ Input consists of 255/1 matched autozeroed comparators
 ☐ No missing codes over temperature range
 ☐ Linearity +1 25 L SB max
- ☐ Linearity ±1.25 LSB max.
- ☐ Three-state outputs
- □ Overrange output
- ☐ Operates from single +5 V supply
- ☐ Low power consumption (50 mW)

Ordering Information

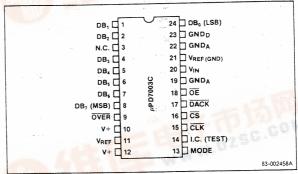
Part Number	Package	Operating Temperature Range
μP07003C	Plastic DIP	-20°C to +70°C

Absolute Maximum Ratings

Analog GND Voltage	±0.3
Power Dissipation	300 mV
Power Supply	-0.3 to +7 \
All Input Voltages	-0.3 to V+ +0.3 \
Storage Temperature	−65 to +125°C
Operating Temperature	-20 to +70°C

Comment: Stress above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Pin Configuration



Pin Identification

Pin	Name	Function
1	DB ₁	7th bit output
2	DB ₂	6th bit output
3	NC	Non connection
4	DB ₃	5th bit output
5	DB ₄	4th bit output
6	DB ₅	3th bit output
7	DB ₆	2th bit output
8	DB ₇	MSB output
9	OVER	Overrange output
10	V+	Power supply (+5 V)
11	VREF	Reference voltage input (positive)
12	V+	Power supply (+5 V)
13	MODE	MODE control (note 1)
14	TEST	Low: Device test (used for inspecting the device) High: Conversion
15	CLK	Low: Previous data output High: Quantizing
16	CS	Chip select
17	DACK	DMA Acknowledge
18	ŌĒ	Low: Data output High: High impedance
19	AGND	Analog ground
20	VIN	Voltage input
21	V _{REF(GND)}	GND for V _{REF}
22	AGND	Analog ground
23	GND	Digital ground
24	DB _O (LSB)	LSB





Pin Identification (Cont.)

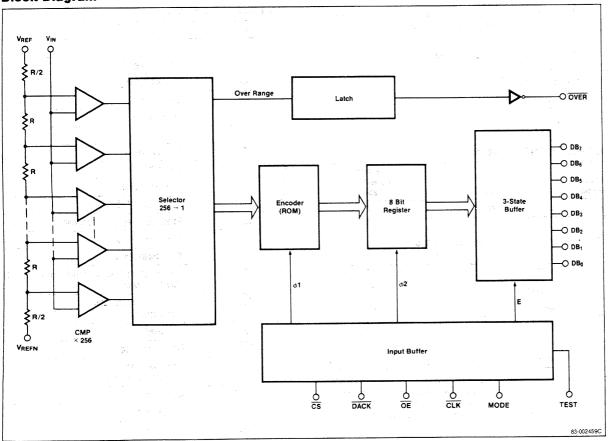
Pin	Name	Function
19	GNDA	Analog ground
20	VSIN	Analog input
21	VREFN	Reference voltage input (negative) (Note 2)
22	GNDA	Analog ground
23	GND _D	Digital Ground
24	DBO	LSB output

Notes: 1.

	Inputs				
Mode	ŌĒ	8-Bit Register			
1	1	Data refreshed with every CONV 1			
•	0	- -			
n	1	 Tanaké			
	0	No change			

2. Tie to the analog ground unless external zero adjustment required

Block Diagram





DC Characteristics

 $T_A = +25 \,^{\circ}C$, $V+ = V_{REF} = 5.0 \pm 0.25 \,^{\circ}V$

		Lim	Limits			Test	
Parameter	Symbol	Min.	Тур.		Unit	Conditions	
Power Supply Current	Icc	2.1	6.0	18.0	mA	$t_{ extsf{CY}} = 4.0~\mu extsf{s}, t_{ extsf{WLC}} = 2.0~\mu extsf{s}$ Note 1	
High Level Output Voltage	VOH	2.8	:		٧	$I_0=-2.0$ mA	
Low Level Output Voltage	VOL			0.4	٧	$I_0 = -1.0 \text{ mA}$	
Digital Input Leakage Current	lilk		-1	10	μ A	$0 \text{ V} \leq \text{V}_{\text{IN}} \leq \text{V} +$	
Digital Output Leakage Current	IOLK		. 1	10	μA	$0 \text{ V} \leq \text{V}_0 \leq \text{V} +$	
Reference Input Current	IREF	1.19	1.79	3.57	mA	CLK = H or L Note 1	
Analog Input Resistance	RIN	1	35		kΩ	$V_{\sf EN}=$ 2.5 V, t _{CY} $=$ 4 μ s, t _{WLC} $=$ 2 μ s Note 2	
Reference Input Capacitance	CREF		100		pF	$f_{clk} = 1$ MHz; unmeasured pins returned to Ground	
Analog Input Capacitance	CIN		100		pF	$f_{ m clk}=1$ MHz; unmeasured pins returned to Ground	
Power Dissipation	PD			50	mW	$t_{ extsf{CY}} = 4.0~\mu extsf{s}, t_{ extsf{WLC}} = 2.0~\mu extsf{s}$	

Notes: 1. This means DC current. Tie the bypass capacitors (electrolytic capacitor \geq 10 μ F, ceramic capacitor \approx 0.01 μ F) to V+ and V_{REF} pins, in order to absorb rush current (\approx 10 mA).

2. DC input equivalent circuit is shown below.

Tie the bypass capacitor (> 0.01 μF) to the analog input pin. 3 mA peak current flows into this pin.

AC Characteristics

 $T_A = 25 \pm 2$ °C; V + = 5.0 V

. 1		Limits			Test	
Parameter	Symbol Min.	Symbol Min. Typ. Max		Unit	Conditions	
	tDEO	100	350	ns	ŌĒ↓ → DO	
Output	toco	150	450	ns	CONV - DO	
Delay Time	toso	100	350	ns	CS ↓ → DO	
	†DCOVR	100	350	ns	CONV 1 - OVER	
Delay Time to Floating	tFEO	70	200	ns	ŌĒ 1 — DO	
	tFSO	150	450	пѕ	CS 1 → DO	

Conversion Characteristics

 $T_A = 25 \pm 2$ °C; V+ = $V_{REF} = 5.0$ V; $t_{CY} = 4.0 \ \mu s$; $t_{WLC} = 2.0 \ \mu s$

100			Limit	ts		Test Conditions
Parameter	Symbol	Min.	Typ.	Max.	Unit	
Resolution	RES	8	8	8	Bits	-20°C to +80°C
Nonlinearity	NL			±1.25	LSB	kii (
Full Scale Error	-			±1.00	LSB	
Full Scale Error Tem- perature Coefficient			20		ppm/°C	
Zero Scale Error		-0.75	j	+0.75	LSB	
Zero Scale Error Tem- perature Coefficient			-20		ppm/°C	

Note: μ PD7003C: $T_A = 0^{\circ}$ C to +70°C.



Recommended Operating Conditions

 $T_A = 0$ °C to 70°C: μ PD7003C,

 $T_A = -20$ °C to +80°C: μ PD7003D

-			Limi	ts		Test
Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Supply Voltage	۷+	4.75	5.0	5.25	V	
Reference Input Voltage	VREF	4.0	V +	V+	V	
Analog Input Voltage	ViN	-0.1		V+ +0.1	۷.	
High Level Logic Input	VIH	2.4		V+	V .	
Low Level Logic Input	VIL	-0.1		0.8	۷	
Sampling Rate		10		250k	times/s	
Conversion Cycle Time	tCY	4.0		100	μ	
CONV High Level Width	twhc	2.0			μ\$	
CONV Low Level Width	twlc	2.0			μ\$	
CONV Setup Time	tsce	0		Note 1	ns	CONV ↓ → OE (
CS Setup Time	tsse	100		,	ns	$\overline{CS} \downarrow \rightarrow \overline{OE} \downarrow$
CS Hold Time	thes	0			ns	OE ↑ → CS ↑
OE Setup Time	tsec	600			ns	OE 1 - CONV
OE Hold Time	tHCE	400			ns	CONV ↑ → OE
OE Low Level Width	twle	400		Note 2	ns	
Digital Input Rise and Fall Time	t _r . t _f			50	ns	

Notes: 1. t_{SCE} (ns) $\leq t_{CY}$ (ns) $-t_{WLE}$ (ns) - 100 (ns).

2. t_{WLE} (ns) $\leq t_{CY}$ (ns) $-t_{SCE}$ (ns) -100 (ns).

Converter Operation

Referring to the block diagram, the reference voltage is set externally to some desired level which references the individual internal components such that V_{REF} is divided equally by 256 resistors in a ladder/divider configuration. The applied voltage to V_{IN} is then compared to the reference level and the individual samples are sent to the selector section where the individual signals are multiplexed to form an address data word. The data word is then further encoded to form the final 8-bit data byte by the encoder ROM, and stored in the 8-bit register until the Output Enable Command. Then the data is sent to the data bus via a three-state buffer.

Mode Select

There are two modes of operation for the μ PD7003. Figure 1 shows the timing diagram for mode "0" where the converter is operating in continuous output mode. The analog input is sampled when the clock is in the "low" state. When the clock is in the "high" state the conversion from analog-to-digital takes place and the resultant data is output on the next falling edge of the clock pulse and the cycle is repeated.

The second mode (Mode 1) is shown in figure 2. In this mode of operation, one conversion takes place while the clock is in the "low" state and the resultant data is held as long as output enable and Chip Select (CS) or DMA Acknowledge (DACK) are "low." Data refresh is inhibited until CS and DACK are recycled.

MODE = "HIGH"

Data is refreshed on the falling edge of $\overline{\text{CLK}}$, loaded during the "low" clock state, and converted and output during the "high" clock state.

MODE = "LOW"

Data is loaded and converted when Output Enable is "low" and refreshed only when \overline{OE} makes the transition from high to low again.

Note that in either case data will only be accepted and output when \overline{OE} and \overline{CS} or \overline{DACK} are active ("low"). Output enable should not be changed during the intervals shown in figure 3. The timing for output enable change versus clock transition is 600 ns before and 500 ns after the rising or falling edge of \overline{CLK} any attempt to change \overline{OE} during these periods will be inhibited.



Timing Waveforms

Figure 1. (MODE;0)

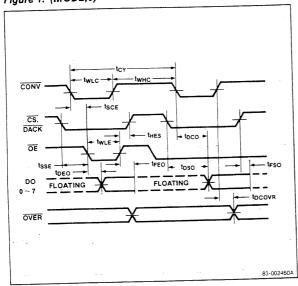
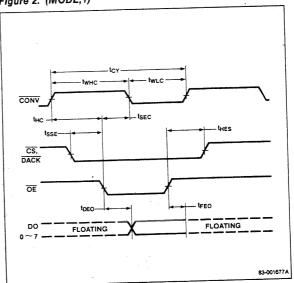
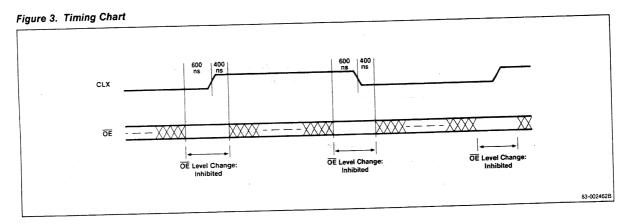


Figure 2. (MODE;1)



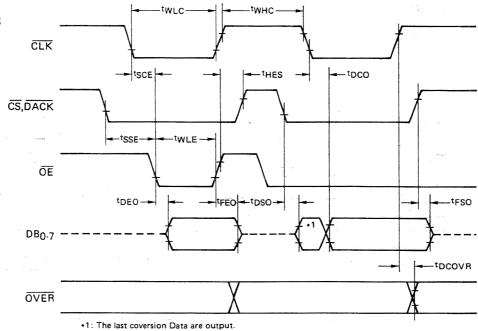


μ PD7003

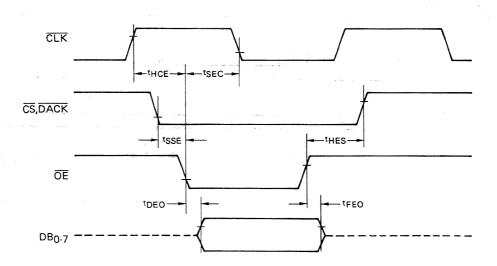


TIMING DIAGRAMS

1. CONTINUOUS OUTPUT MODE



2. LATCH OUTPUT MODE



OPERATION OF INTERNAL CIRCUIT BLOCK

1. COMPARATOR

Reference voltage (V_{REF}) is divided by 256 resistors, and 256 comparators simultaneously compare analog input voltage (V_{IN}) with the divided voltages.

2. SELECTOR, ENCODER

Selector accepts the outputs of comparators, and detects the position of comparator which corresponds to analog input voltage.

The encoder generates an 8 bit code by translating the output data from selector.

When the analog input voltage (V_{IN}) is higher than the reference voltage (V_{REF}), the selector generates an over range signal (\overline{OVER}).

3.8-BIT LATCH

This register temporally stores 8-Bit data from encoder.

4. LOGIC CONTROL

This circuit block generates internal control signals according to external control signals.



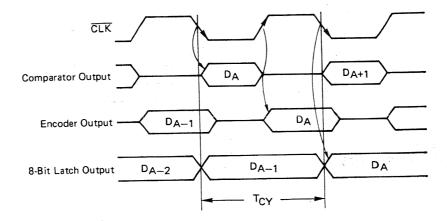
OPERATION MODES

According to the different conversion output, two modes of operation are available.

1. CONTINUOUS OUTPUT MODE (MODE = H)

The actual conversion time of $\mu PD7003$ is shortened by using pipeline processing mode.

INTERNAL TIMING

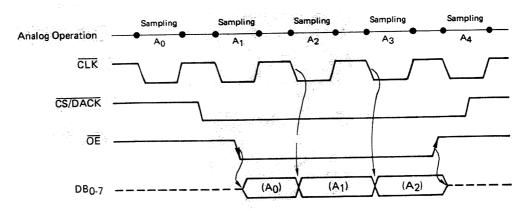


The pipeline processing consists of 3 steps:

- Comparing by comparators,
 Generating 8-Bit data in selector and encoder,
- Holding conversion data in 8-Bit latch.

Analog input signals are sampled at the low level interval of CLK. The conversion data are output at the subsequent falling edge of CLK.

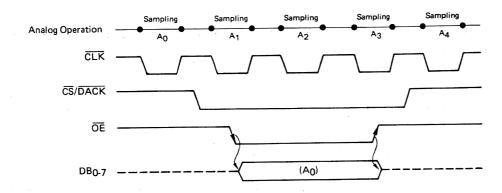
CONTINUOUS **OUTPUT** MODE TIMING



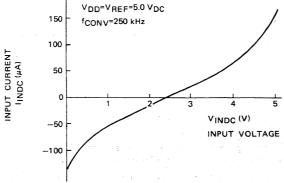


2. LATCH OUTPUT MODE (MODE = L)

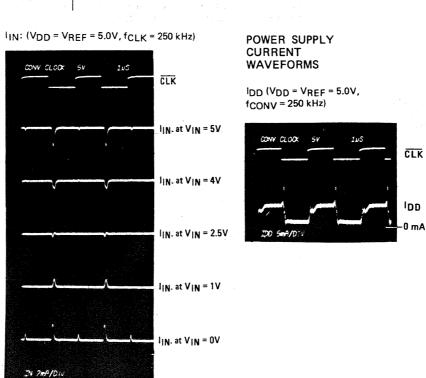
In this mode, μ PD7003 operates the same A/D conversion operation as continuous output mode, but with an additional 8-Bit latch operation. In latch output mode, updating of 8-Bit latch data is inhibited at the low level interval of \overline{OE} , and holding the last latched data.



INPUT CHARACTERISTICS



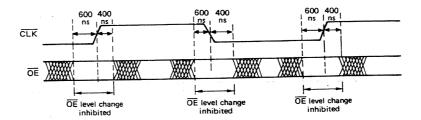
INPUT CURRENT WAVEFORMS



APPLICATION HINTS

Note 1: Data of A₁ and A₂ are not held.

Note 2: Please do not change the level of \overline{OE} signal during the intervals shown below.





Packaging Information

24-Pin Plastic Package (600 mil)

